



PK500 (v1.1) March 19, 2012

## 100% Material Declaration Data Sheet for Spartan®-3 FG900 (Cu Wire) Package

**Average Weight: 3.949 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					<b>0.107655</b>	<b>2.726</b>
	Silicon	7440-21-3	100.00		0.107655	
Die Attach Material					<b>0.018830</b>	<b>0.477</b>
	Silver	7440-22-4	77.50		0.014593	
	Bismaleimide monomer	Trade Secret	15.00		0.002825	
	Acrylate monomer	Trade Secret	7.50		0.001412	
Mold Compound					<b>1.862156</b>	<b>47.155</b>
	Solid Epoxy Resin	Trade Secret	5.00		0.093108	
	Phenol Resin	Trade Secret	3.00		0.055865	
	Phenol Novolac	9003-35-4	3.00		0.055865	
	Metal Hydroxide	Trade Secret	3.00		0.055865	
	Carbon Black	1333-86-4	0.30		0.005586	
	Silica fused	60676-86-0	70.40		1.310958	
	Silicon Dioxide	7631-86-9	15.00		0.279323	
	Silica, crystalline	14808-60-7	0.30		0.005586	
Copper Wire					<b>0.009371</b>	<b>0.237</b>
	Copper	7440-50-8	97.28		0.009116	
	Palladium	7440-05-3	2.70		0.000253	
	Impurities	NA	0.02		0.000002	
Solder Balls					<b>0.753863</b>	<b>19.090</b>
	Tin (Sn)	7440-31-5	63.00		0.474934	
	Lead (Pb)	7439-92-1	37.00		0.278929	

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Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Substrate					1.197125	30.315
	Copper (Cu)	7440-50-8	40.58		0.485793	
	Nickel (Ni)	7440-02-0	0.33		0.003951	
	Gold (Au)	7440-57-5	1.52		0.018196	
	Glass fiber	65997-17-3	5.58		0.066800	
	Non halogen fire retardant	NA	0.10		0.001197	
	BT (core)	21645-51-2 105391-33-1 25722-66-1 9003-36-5 21645-51-2	45.21		0.541220	
	Solder mask	14807-96-6 7727-43-7 7631-86-9 34590-94-8 85954-11-6	6.68		0.079968	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
09/16/11	1.0	Initial Xilinx release.
03/19/12	1.1	Device family update.

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